

# NCE N-Channel Enhancement Mode Power MOSFET

### Description

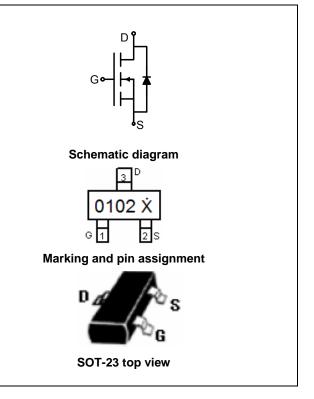
The NCE0102 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### **General Features**

- $V_{DS} = 100V, I_D = 2A$   $R_{DS(ON)} < 240m\Omega @ V_{GS} = 10V$  (Typ:210m $\Omega$ )  $R_{DS(ON)} < 260m\Omega @ V_{GS} = 4.5V$  (Typ:220m $\Omega$ )
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity	
0102 X	NCE0102	SOT-23	Ø180mm	8 mm	3000 units	

### Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	Vds	100	V	
Gate-Source Voltage	V <sub>GS</sub>	±20	V	
Drain Current-Continuous	I <sub>D</sub>	2	А	
Drain Current-Continuous(T <sub>C</sub> =100℃)	I <sub>D</sub> (100℃)	1.4	А	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	8	А	
Maximum Power Dissipation	PD	1.25	W	
Avalanche Current (Note 1)	I <sub>AR</sub>	2	А	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	2.45	mJ	
Reverse diode dv/dt, VDs <80 V, IsD <id< td=""><td>dv/dt</td><td>15</td><td>V/ns</td></id<>	dv/dt	15	V/ns	
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	°C	

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>0JA</sub>	100	°C <b>/W</b>



# Electrical Characteristics (T\_A=25 $^\circ\!\mathrm{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		•
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	100	110	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
On Characteristics (Note 3)			•	•		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.2	1.8	2.5	V
	5	V <sub>GS</sub> =10V, I <sub>D</sub> =2A	-	210	240	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A	-	220	260	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =2A	1	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>		-	360.6	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,	-	24.6	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	13	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	6	-	nS
Turn-on Rise Time	tr	$V_{DD}$ =50V, R <sub>L</sub> =25 $\Omega$	-	10	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{G}$ =1 $\Omega$	-	12	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS
Total Gate Charge	Qg		-	12.0		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =50V,I <sub>D</sub> =2A,	-	1.8	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	2.9	-	nC
Drain-Source Diode Characteristics	I I		<b>I</b>			1
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =2A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	2	Α

#### Notes:

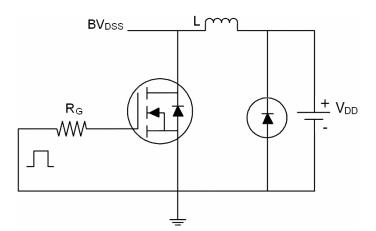
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production

 $\textbf{5.EAS condition}: Tj = 25^\circ C, V_{DD} = 50V, V_G = 10V, L = 0.5mH, Rg = 25\Omega$ 

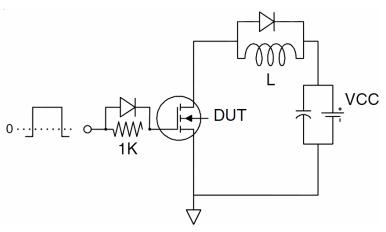


# **Test Circuit**

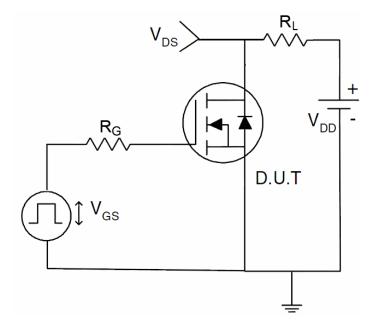
1) E<sub>AS</sub> test circuit

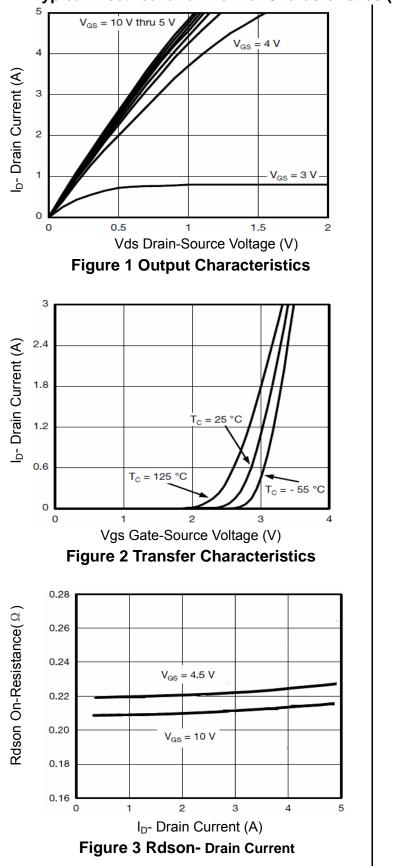


### 2) Gate charge test circuit

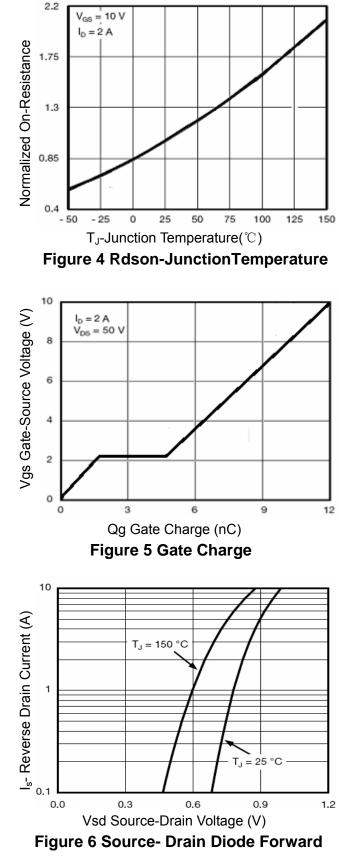


3) Switch Time Test Circuit

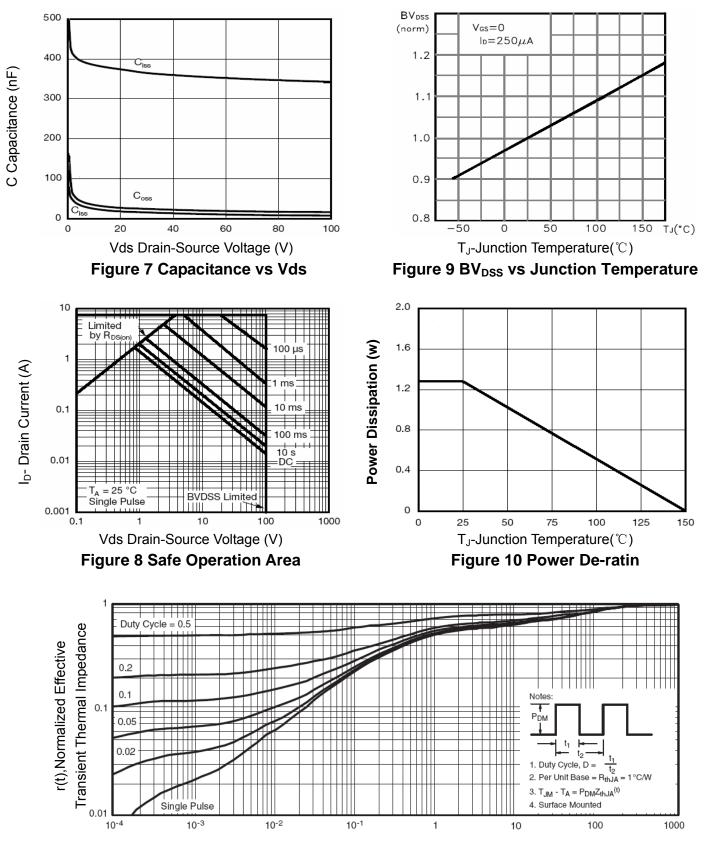


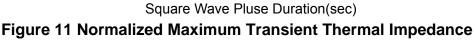


# **Typical Electrical and Thermal Characteristics (Curves)**



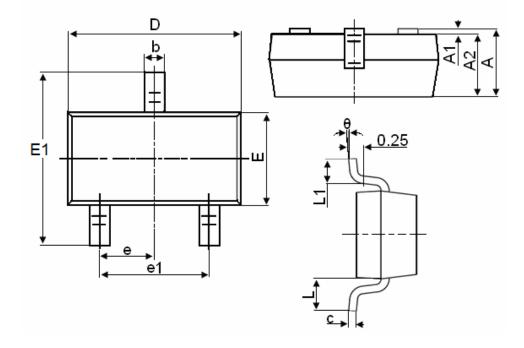








# **SOT-23 Package Information**



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
A	0.900	1.150	
A1	0.000	0.100	
A2	0.900	1.050	
b	0.300	0.500	
с	0.080	0.150	
D	2.800	3.000	
E	1.200	1.400	
E1	2.250	2.550	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.500	
θ	0°	8°	

### Notes

1. All dimensions are in millimeters.

2. Tolerance ±0.10mm (4 mil) unless otherwise specified

3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.

4. Dimension L is measured in gauge plane.

5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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